

**REMARKS**

The Office Action mailed October 29, 2007 has been received and carefully considered. Claims 1-4 have been amended and new claims 5-12 have been added.

**Claims 1-12 are now pending in the Application and are submitted to be in allowable condition.**

**Claim Changes and Support**

The changes to claim 1 are supported in paragraph [0024] of the Application as-filed.

New claims 5 and 6 find support in paragraph [0024] and Fig. 2 of the Application as-filed.

New independent claim 7 finds support in original claim 1 and the paragraph bridging pages 14 and 15 of the Application as-filed.

New claims 8 and 9 are supported by original claims 3 and 4, respectively.

New claim 10 finds support in paragraph [0024] and Fig. 2 of the Application as-filed.

New claims 11 and 12 are supported by claims 5 and 6, paragraph [0024], and Fig. 2 of the Application as-filed.

**I. The rejection of claims 1 and 2 under 35 U.S.C. §102(b) as anticipated by Haitz et al. (US 5,917,202) is respectfully traversed in view of the .**

**II. The rejection of claims 3 and 4 under 35 U.S.C. §103(a) as unpatentably obvious over Haitz et al. (US 5,917,202) is respectfully traversed.**

Remarks Distinguishing Over The Prior Art

Haitz et al. discloses a way to minimize the size of contacts on an LED to suppress absorption of light generated by the LED. The device shown in Fig. 4 of Haitz et al. is formed by a compound semiconductor wafer that includes a GaP substrate and LED device layers bonded onto the substrate. The device includes minute ohmic contact metallizations distributed on the back surface of the GaP substrate and a reflective contact metallization covering both the ohmic contact metallizations and the dielectric layer. The ohmic contact metallizations or the micro-alloyed areas may have a variety of shapes including circular, elliptical, square, or annular rings (see Col. 5, lines 16-18).

However, from a reading of this disclosure as a whole, one of ordinary skill in this art would understand that Haitz et al. intend a structure that has a plurality of separated micro-alloyed areas formed on the back surface of the substrate (see, for example, Col. 1, line 64 "small alloyed dots"; Col. 2, lines 50-53, and Col. 4, lines 14-22).

The present invention is distinguishable in that Applicants' rear surface electrode is required to have "*a pattern which is a continuous line distributed on the entire back surface of the substrate*" (see claim 1 as amended). Applicants submit that such a structure is neither taught nor suggested by the disclosure of Haitz et al. so that claims

1 and 2 are not anticipated by Haitz et al. and this ground of rejection should be withdrawn.

Moreover, Applicants submit that such a structure is neither taught nor suggested by the disclosure of Haitz et al. so that claims 3 and 4 may not be fairly said to be rendered obvious by the disclosure of Haitz et al. and this ground of rejection should be withdrawn as well.

Note that new claims 5 and 6 further limit the specific shape of the pattern of the continuous line, so that new claims 5 and 6 are submitted to be further distinguishable over Haitz et al. on this basis as well.

Regarding new claim 7, the disclosure of Haitz et al. does not teach or suggest *"...a reflection layer which is deposited in contact with the rear surface electrode, which covers the rear surface electrode and the rear surface insulation layer, which has a greater reflectivity with respect to the light emitted from the semiconductor light emitting portion than the rear surface electrode, which has an interface with the blazing material disposed between the reflection layer and the mounting board, and which is composed of a material which is electrically conductive and which has a reflectivity observed at an interface between the rear surface insulation layer and the material that is higher than a reflectivity observed at an interface between the surface of the electrically conductive substrate and the blazing material with respect to the light emitted from the semiconductor light emitting portion"* (see new claim 7). For at least this distinguishing feature, Applicants submit that new claim 7 is structurally differentiated from the

disclosure of Haitz et al. so that the light emitting assembly recited in new claim 7 is neither taught nor suggested by the disclosure of Haitz et al.

New claims 8-12 further differentiate the present invention from the disclosure of Haitz et al. for reasons analogous to those given in the foregoing.

Applicants therefore submit that the disclosure of Haitz et al. does not meet Applicants' claims 1-4 as amended or Applicants' new claims 5-12 so that no *prima facie* case of obviousness is set forth so that made out the claim as amended for which reason this rejection should be withdrawn.

### **CONCLUSION**

In view of the foregoing amendments and remarks, Applicants submit that claims 1-12, and the Application are in condition for allowance. Reconsideration and passage of this case to issue are therefore requested.

Should the Examiner consider that a conference would help to expedite the prosecution of this Application, the Examiner is invited to contact the undersigned to arrange for such an interview.

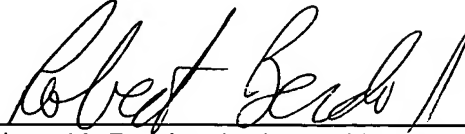
No fee is believed due. If any fee is deemed due, the Director is hereby

authorized to charge the same to our Deposit Account No, 18-0002 and is requested to advise us accordingly.

Respectfully submitted,

January 23, 2008

Date



Robert H. Berdo, Jr. (Reg. No. 38,075)

Rabin and Berdo, PC

CUSTOMER NO. 23995

1101 - 14<sup>th</sup> Street, N.W., Suite 500

Washington, D.C. 20005

Tel.: (202) 371-8976

Fax: (202) 408-0924

RHB/AJW/vm